Harvatek Surface Mount CHIP LEDs Data Sheet B2612UDNB05D000512U1930

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Tentative Product	***************************************				
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DISCLAIMER
LIFE SUPPORT POLICY
PRODUCT SPECIFICATIONS
ATTENTION: ELECTROSTATIC DISCHARGE (ESD) PROTECTION4
LABEL SPECIFICATIONS
SPECIFICATIONS RANGE
PRODUCT FEATURES
ELECTRO-OPTICAL CHARACTERISTICS
PACKAGE OUTLINE DIMENSION AND RECOMMENDED SOLDERING PATTERN FOR REFLOW
Soldering
Absolute Maximum Ratings7
CHARACTERISTICS OF B2612UDNB8
PRECAUTION FOR USE
PRECAUTION FOR USE
PACKAGING 10
PACKAGING

7				
Official Product	HT Part No. B2612UDNB05D000512U1930			
Tentative Product	***************************************			
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DISCLAIMER

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.

2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

7				
Official Product	HT Part No. B2612UDNB05D000512U1930			
Tentative Product	***************************************			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		03/12/2021	Version 1.1	Page 3/14

Product Specifications

Specification	Material	Quantity
UD:18-71.5 mcd		
NB:11.25-45 mcd		
@5mA/ T _s = 25°C ;Tolerance: \pm 10%		
UD:600.0-612.0 nm		
NB:460.0-475.0 nm		
@5mA/ T _S = 25 $^{\circ}$ C ;Tolerance: <u>+</u> 0.5nm		
UD:1.6-2.4V		
NB:2.55-3.15V		
@5mA/ T_s= 25 $^\circ\!\!\mathbb{C}$;Tolerance: <u>+</u> 0.05V		
< 10 µA @ V _R = 5 V		
Diffused	Ероху	
EIA 481-1A specs	Conductive black tape	
EIA 481-1A specs	Conductive black	
HT standard	Paper	
220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
HT standard	Paper	Non-specified
	UD:18-71.5 mcd NB:11.25-45 mcd $@5mA/T_s= 25^{\circ}C$;Tolerance: $\pm 10^{\circ}$ UD:600.0-612.0 nm NB:460.0-475.0 nm $@5mA/T_s= 25^{\circ}C$;Tolerance: ± 0.5 nm UD:1.6-2.4V NB:2.55-3.15V $@5mA/T_s= 25^{\circ}C$;Tolerance: ± 0.05 V $< 10 \ \mu A \ @ \ V_R = 5 \ V$ Diffused EIA 481-1A specs EIA 481-1A specs HT standard 220x240mm	Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of the system Image: state of

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin

combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note :This is shipped test conditions

%Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product,

such operation can cause migration resulting in LED damage.

ATTENTION: Electrostatic Discharge (ESD) protection



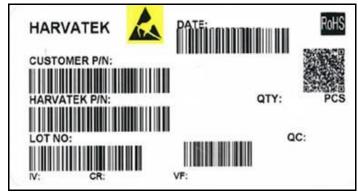
The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

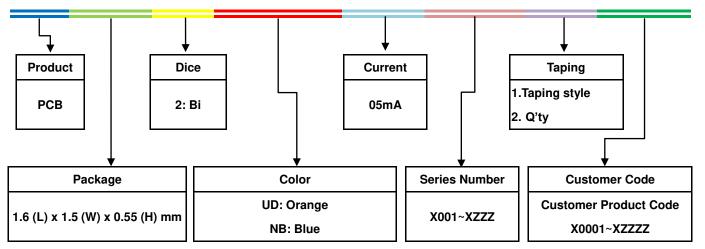
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Official Product	HT Part No. B2612UDNB05D000512U1930			
Tentative Product	***************************************			
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Label Specifications



Harvatek P/N:

B 261 2 UDNB 05D 0005 12 U1930



Lot No.:

1	2	3	4	5	6	7	8	9	10
E	1	Α	1	Α	2	2	L	1	2
Cod	e 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
		Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special cod	e
		2010-A		1:A					
		2011-B		2:B					
		2012-C	1:Jan.	3:C					
			2:Feb.						
Internal Tre	aning Code	2018-I/J		26:Z	01	-ZZ		000~ZZZ	
internal i ra	acing Code	2019-K	A:Oct.	27:7	01-	-22		000~222	
			B:Nov.	28:8					
		2022-N	C:Dec.	29:9					
		2023-P	10.000	30:3					
				31:4					

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Tentative Product	***************************************				
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Specifications Range

Luminous Intensity (Iv) Bin:

Color	Bin Code	Spec. Range
	М	18.00-28.50 mcd
UD	N	28.50-45.00 mcd
	Р	45.00-71.50 mcd
	L	11.25-18.00 mcd
NB	М	18.00-28.50 mcd
	N	28.50-45.00 mcd

Note: It maintains a tolerance of ±10% on luminous intensity

Wavelength Bin:

Color	Bin Code	Spec. Range
UD	В	600.0-603.0 nm
	С	603.0-606.0 nm
	D	606.0-609.0 nm
	E	609.0-612.0 nm
	AA	460.0-465.0 nm
NB	AB	465.0-470.0 nm
	AC	470.0-475.0 nm

Note: It maintains a tolerance of \pm 0.5nm on Wavelength Bin

Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range
UD	E18	1.6-2.4 V
	G2T	2.55-2.65 V
	G3T	2.65-2.75 V
	G4T	2.75-2.85 V
NB	H1T	2.85-2.95 V
	H2T	2.95-3.05 V
	НЗТ	3.05-3.15 V

Note: It maintains a tolerance of ±0.05V on forward voltage measurements

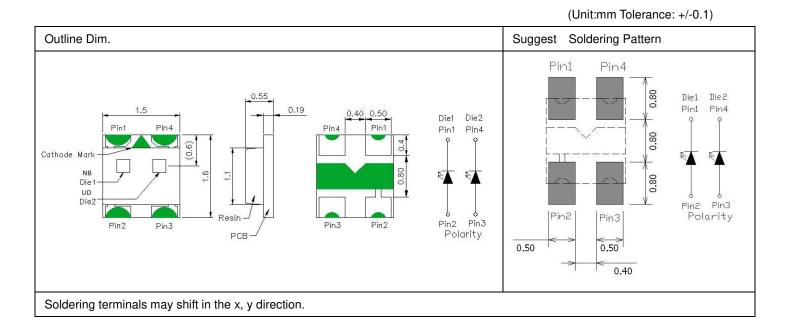
Official Product	HT Part No. B2612UDNB05D000512U1930				
Tentative Product	***************************************				
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Product Features

Electro-Optical Characteristics

	I Gharacteris	1105							
								(T _{Solo}	<u>lering</u> , 25 °C)
Carioa	Emitting Color	Matarial	VF	(V)	Wa	velength λ	(nm)	I _V (mcd)	Viewing
Series	Emitting Color	Material	typ	max	λ_{D}	λ_{P}	Δλ	Typical	Angle $2\theta \frac{1}{2}$
	UD	AlGalnP	2.0	2.4	605	611	611 17	28.5	X=140
	00	AIGaIIIF	2.0	2.4	605	011			Y=120
B2612UDNB05	ND	InGaN	0.0	3.15	472	470	40	19.0	X=140
	NB	Ingan	2.8 3.15	412	470	40	18.0	Y=120	

Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering



Absolute Maximum Ratings

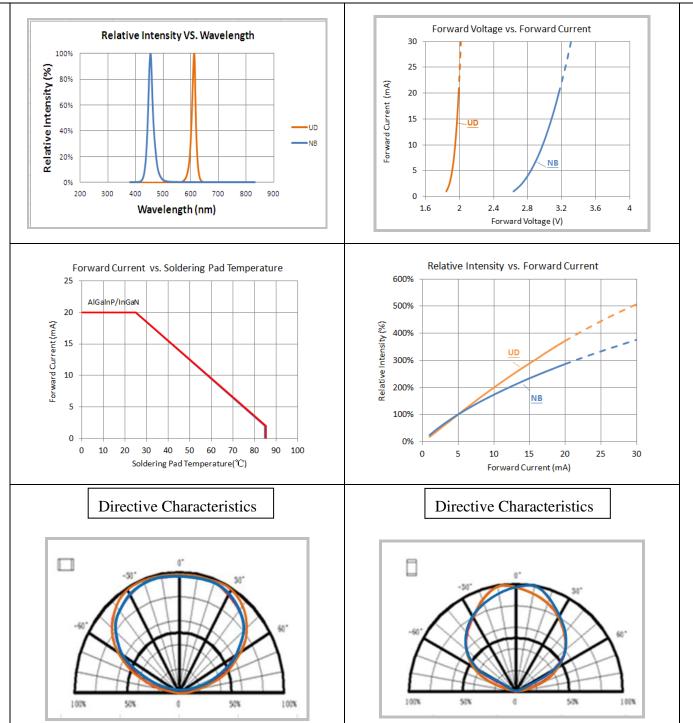
(T _{Soldering}	25	°C)
۰.	 Soldenna 	20	\sim	1

					(• Soldening
Series	P_{D} (mW)	I _F (mA)	I _{FP} (mA)*	Т _{ОР} (°С)	Т _{sт} (°С)
Color	Power	Forward	Pulse Forward	Operating	Storage
COIOI	Dissipation	Current	Current	Temperature	Temperature
UD	48	20	100	-40~+85	-40~+100
NB	63	20	80	-40~+85	-40~+100

*Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

Official Product HT Part No. B2612UDNB05D000512U1930				
Tentative Product	*****	*****		
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Characteristics of B2612UDNB



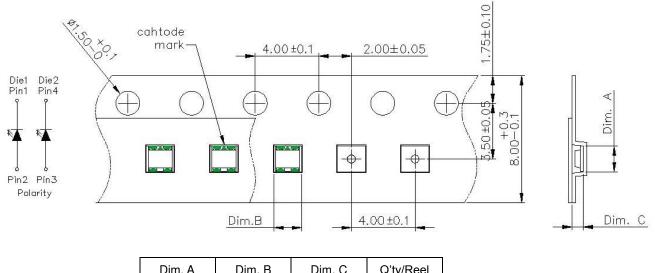
Official Product HT Part No. B2612UDNB05D000512U1930				
Tentative Product	*****	*****		
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Precaution for Use

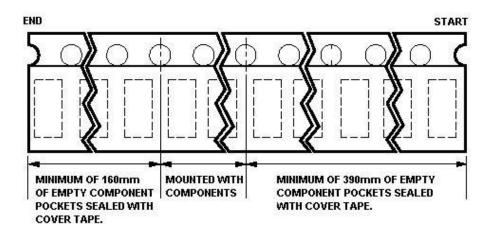
- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The LEDs must be used within 4 weeks after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs.If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs.Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

7				
Official Product	HT Part No. B2612UDNB05D000512U1930			
Tentative Product	******	*****		
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Packaging Tape Dimension

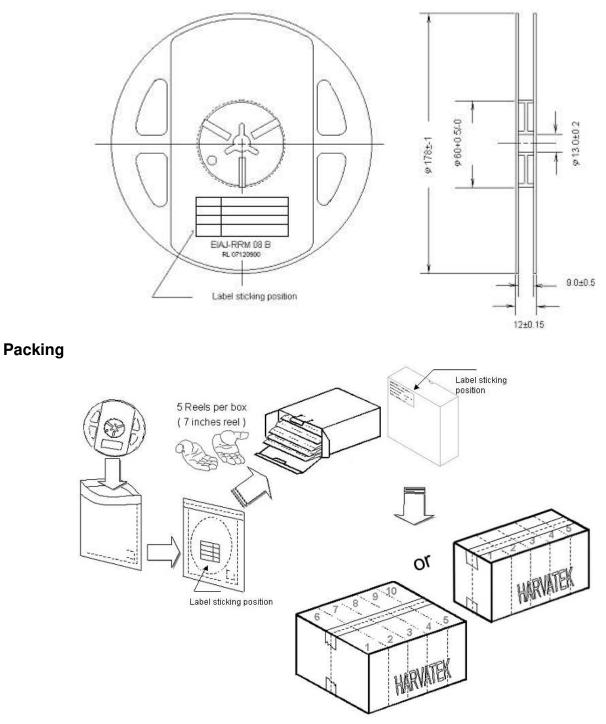


Dim. A	Dim. B	Dim. C	Q'ty/Reel
1.75±0.05	1.65±0.05	0.70±0.05	2K



Official Product	HT Part No. B2612UDNB05D000512U1930				
Tentative Product	*****	*****			
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Reel Dimension



5 or 10 boxes per carton is available depending on shipment quantity.

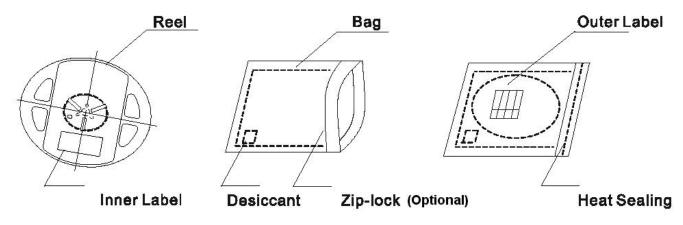
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Official Product	HT Part No. B2612UDNB05D000512U1930			
Tentative Product	*****	*****		
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Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



Baking

Baking before soldering is recommended when the package has been unsealed for 4 weeks. The conditions are as followings:

- 1. $60\pm3^{\circ}C\times(12\sim24hrs)$ and <5% RH, taped reel type.
- 2. 100±3℃×(45min~1hr), bulk type.
- 3. $130\pm3^{\circ}C \times (15\min \sim 30\min)$, bulk type.

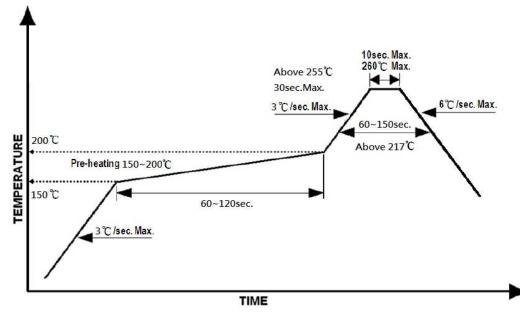
Precautions

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlGaInP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Official Product	uct HT Part No. B2612UDNB05D000512U1930				
Tentative Product	*****	*****			
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Reflow Soldering

- 1. Operating temp.: Above 217° C ,60~150 sec.
- 2. Peak temp.:260°C Max.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:



Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Official Product	HT Part No. B2612UDNB05D000512U1930				
Tentative Product	*****	****			
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Lead-free Solder Profile

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Revise History

Rev.	Descriptions	Date	Page
-	-	08/29/2019	-
1.0	Update to official version	11/07/2019	-
1.1	Add Customer Product Code	03/12/2021	P5

Official Product	HT Part No. B2612UDNB05D000512U1930			
Tentative Product	*****	****		
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